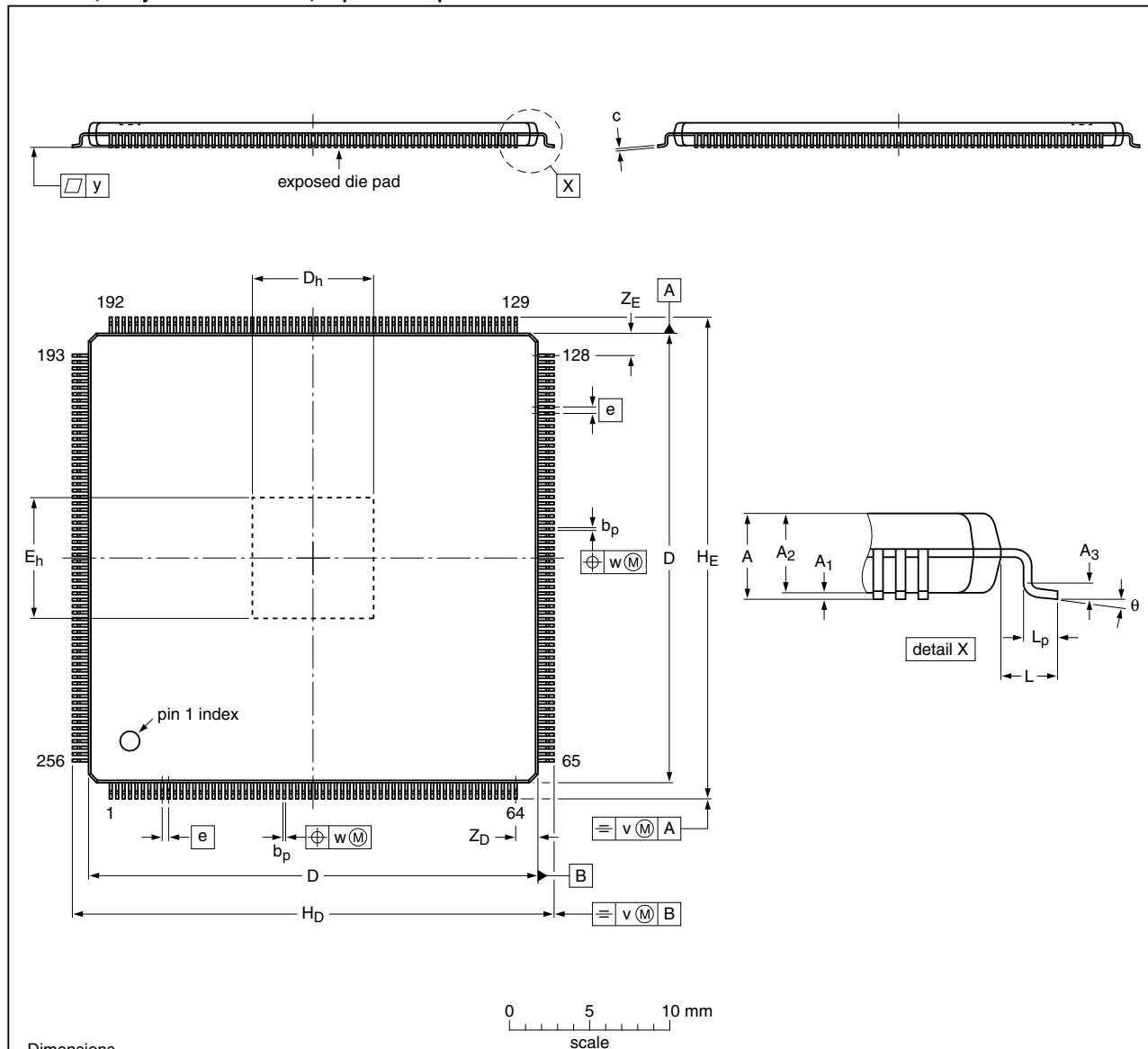


**HLQFP256: plastic thermal enhanced low profile quad flat package;  
256 leads; body 28 x 28 x 1.4 mm; exposed die pad**

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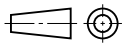
### Dimensions

Unit	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
max	1.6	0.15	1.45		0.23	0.20	28.2	7.64	28.2	7.64		30.2	30.2		0.75		0.07	0.08	1.5	1.5	7.0°
nom	1.5	0.10	1.40	0.25	0.18	0.13	28.0	7.54	28.0	7.54	0.4	30.0	30.0	1	0.60	0.2	0.07	0.08	1.4	1.4	3.5°
min	1.4	0.05	1.35		0.13	0.09	27.8	7.44	27.8	7.44		29.8	29.8		0.45				1.3	1.3	0°

### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot1128-1\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1128-1		MS-026			08-11-04 08-12-19